



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-07-07
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
EMIF02-02OABRY	7A3U*EMIZR1B	A	ZW1A	2016-07-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	22.50	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3x3x0.9	6	No lead	
Comment	Package: DFN.30.30.09-110-6L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7A3U*EMI2R1B					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	Other inorganic materials	1.922	mg	supplier	die	Silicon (Si)	7440-21-3		1.781	mg	926639	79156
				supplier	metallization	Aluminium (Al)	7429-90-5		0.067	mg	34860	2978
				supplier	metallization	Gold (Au)	7440-57-5		0.012	mg	6243	533
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	520	44
				supplier	polymer die coating	Polymer resist - Benzocyclobutene (BCB)	694-87-1		0.061	mg	31738	2711
Leadframe	Copper & its alloys	7.046	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.174	mg	876242	274400
				supplier	alloy	Iron (Fe)	7439-89-6		0.165	mg	23418	7333
				supplier	alloy	Zinc (Zn)	7440-66-6		0.008	mg	1135	358
				supplier	alloy	Iron Phosphide (Fe2P)	1310-43-6		0.007	mg	993	311
				supplier	metallization	Silver (Ag)	7440-22-4		0.692	mg	98212	30756
Die attach	Other Organic Materials	0.181	mg	supplier	glue	Epoxy resin	25068-38-6		0.081	mg	447514	3600
				supplier	glue	Silica	7631-86-9		0.100	mg	552486	4444
Bonding wires	Other inorganic materials	0.010	mg	supplier	wire	Copper (Cu)	7440-50-8		0.010	mg	1000000	444
Encapsulation	Other Organic Materials	12.960	mg	supplier	mold compound	Epoxy resin	25068-38-6		1.166	mg	89969	51822
				supplier	mold compound	Silica fused (SiO2)	60676-86-0		11.147	mg	860108	495422
				supplier	mold compound	Phenolic resin	29690-82-2		0.583	mg	44985	25911
				supplier	mold compound	Carbon black	1333-86-4		0.064	mg	4938	2844
Connections coating	Solder	0.381	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.381	mg	1000000	16933